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General Information

Series	SMD Comm X7R FO
Style	SMD Chip
Description	SMD, MLCC, Open Mode, Temperature Stable
Features	Open Mode, Temperature Stable
RoHS	Yes
Termination	Tin
Marking	No
Typical Component Weight	41 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.6mm +/-0.20mm
S	1.5mm MIN
B	0.5mm +/-0.25mm
Case Code (EIA / mm)	1206 / 3216

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2000
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	3.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	227.3 MOhms

Dimensions

Capacitance	2.2 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	3.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	227.3 MOhms

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